



## 4th Workshop: Elaboration of Recommendations

### Introduction and summary of the previous workshops

Clivia M Sotomayor Torres (ICN)

## About NANO-TEC

- Context
- Objectives

## ACTIVITIES

- Methodology
- Workshops
- Project web site

## OUTCOME SO FAR

- Summary of discussions to date
- Lessons learnt

# CONTEXT

The JU AENEAS covers the whole of nanoelectronics research, *except* the Beyond CMOS Domain.

Beyond CMOS research is carried out mainly in academic and research organisations.

Existing consortia cover several domains including Beyond CMOS, which lacks visibility in the ERA and in the EU Framework program.

Given the existence of the JU AENEAS and the room for the EU to fund Beyond CMOS research, a community with long-term research interests in nanoelectronics is needed.

Of key importance is to address the design issues in Beyond CMOS and build a bridge between technologies and design or, better still from novel device concepts through technologies, systemability, to design for applications.

# POSITION of NANO-TEC

## **Nanofabrication networks, national and EU**

MyFab, RENATECH, Micronova,  
DIMES, TNO, Tyndall, IMEL,  
NANOLITO, ....

## **Design Networks**

EDA centrum  
RD-ACCESS



## **Technology National and EU Networks & projects**

FinNano (FI)  
NANOFUNCTION, SINANO  
CNANO & CNFM (F)  
Linneqs & Gigabit Wave  
(SE)  
nanoTHERM (ES)  
ENI2

## **Interest groups and JTI**

ENIAC Scientific  
Community Council  
AENEAS & CATRENE  
ITRS & SRC (USA)

# OBJECTIVES AND PARTNERS

To identify the next generation of (emerging) device concepts and technologies for ICT.

To build a joint technology-design community to coordinate research efforts in nano-electronics.



**CHALMERS**



## **Thematically:**

**Puts emphasis on Beyond CMOS Devices and Design**

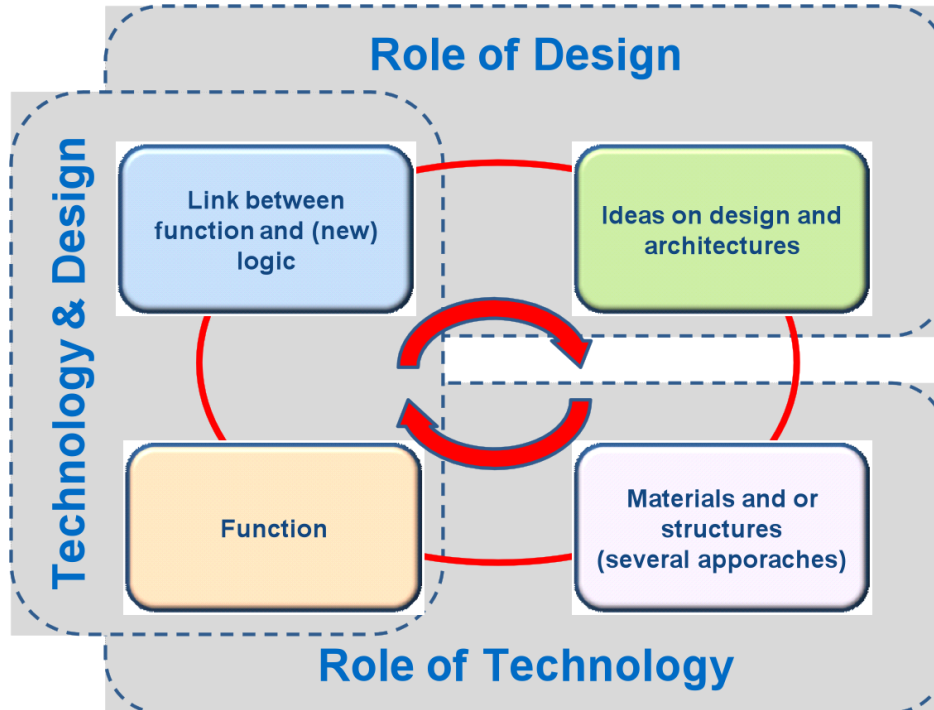
## **As Instrument:**

**Organises and coordinates discussions and makes recommendations**

## **Actors:**

**Mainly from academia and research organisations.  
Industry via Advisory Board.**

# ACTIVITIES

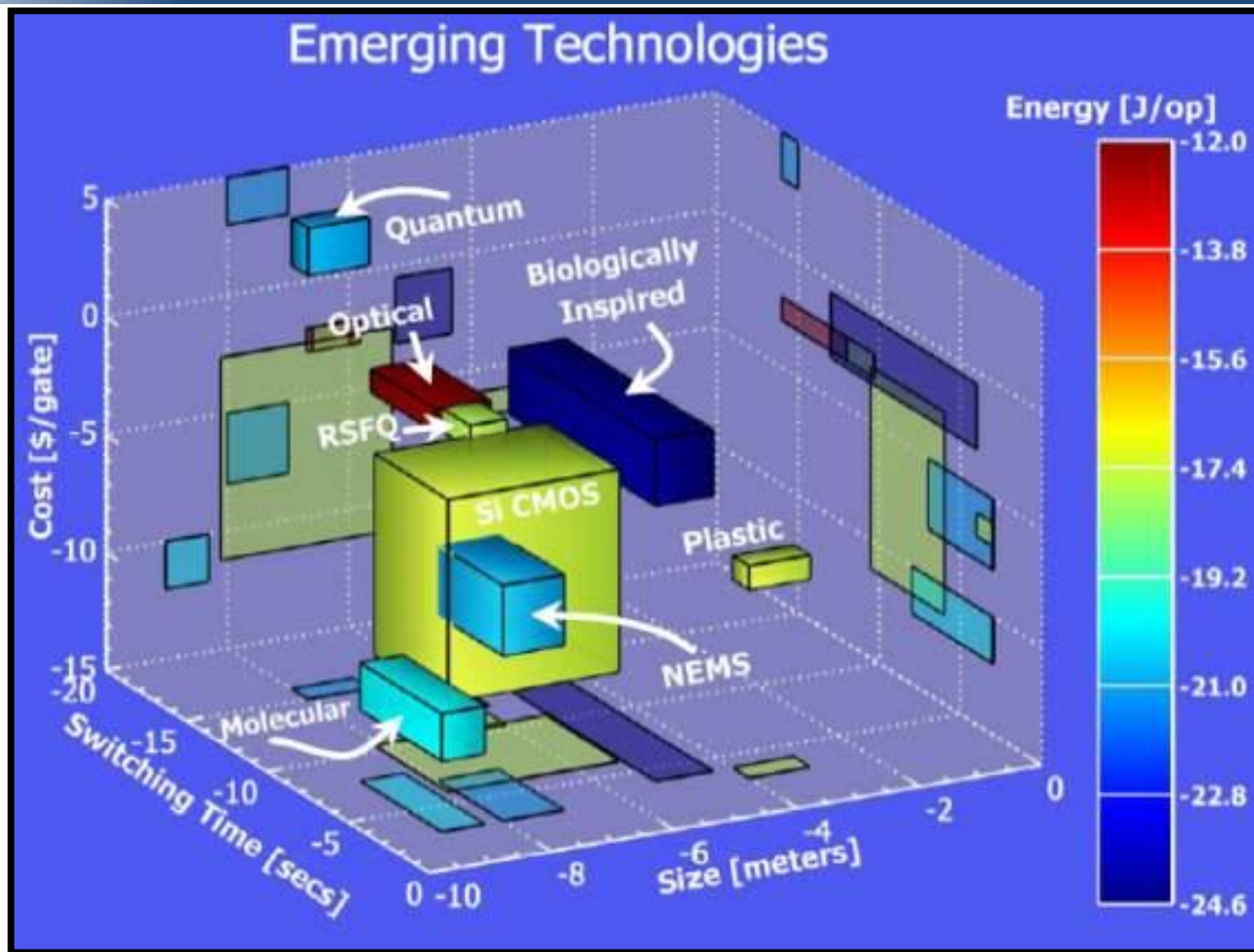


4 workshops with invited experts on Beyond CMOS devices, benchmarking and a SWOT analysis of new devices.

A state-of-the-art web platform for working groups, enabling **discussions fora**, meetings, communications and access to an information repository.

A report on Emerging Nanoelectronics.

# BEYOND CMOS TECHNOLOGIES a la ITRS

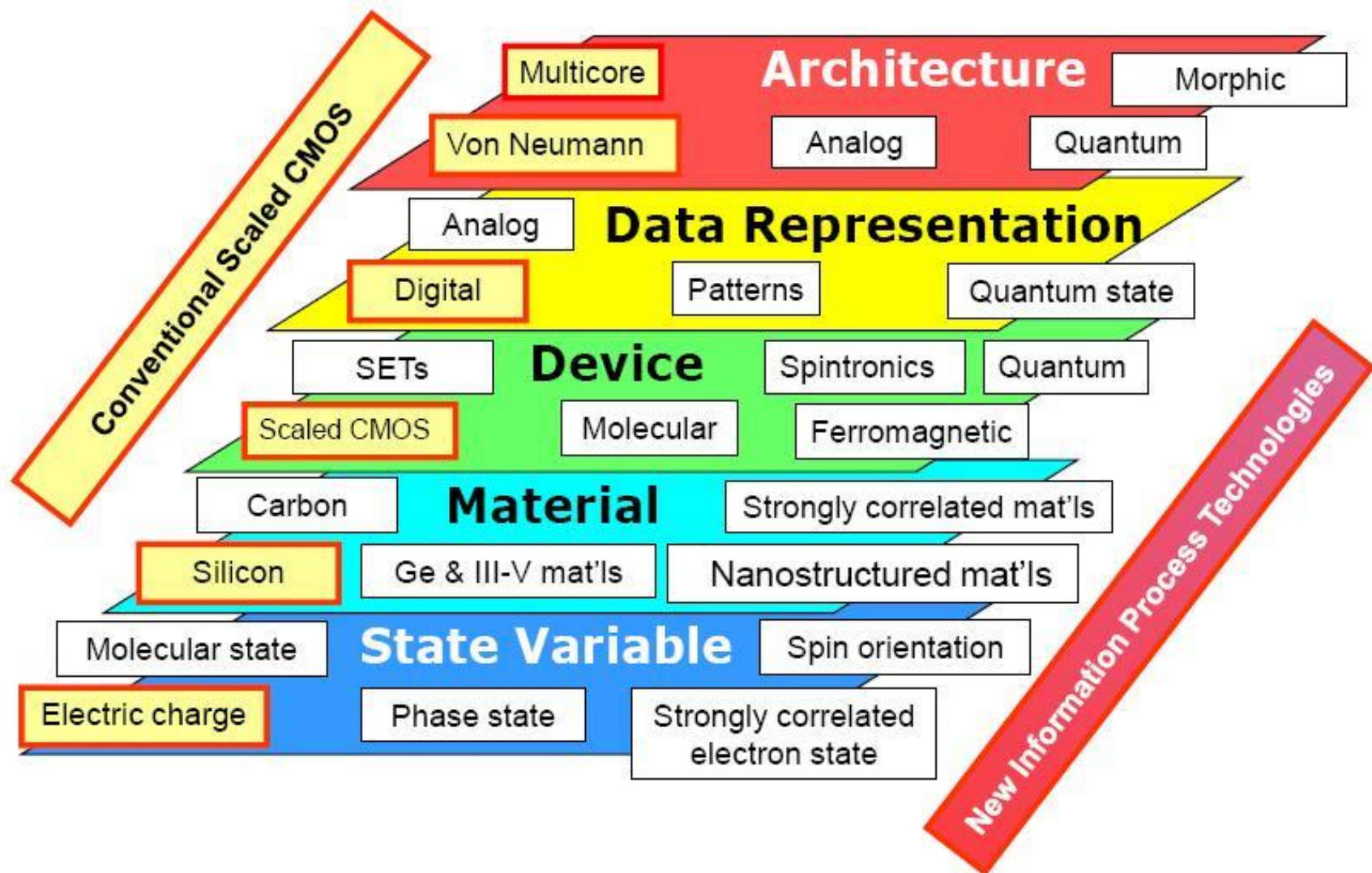


(Reproduced after ERD ITRS)



# BEYOND CMOS TECHNOLOGIES a la EU

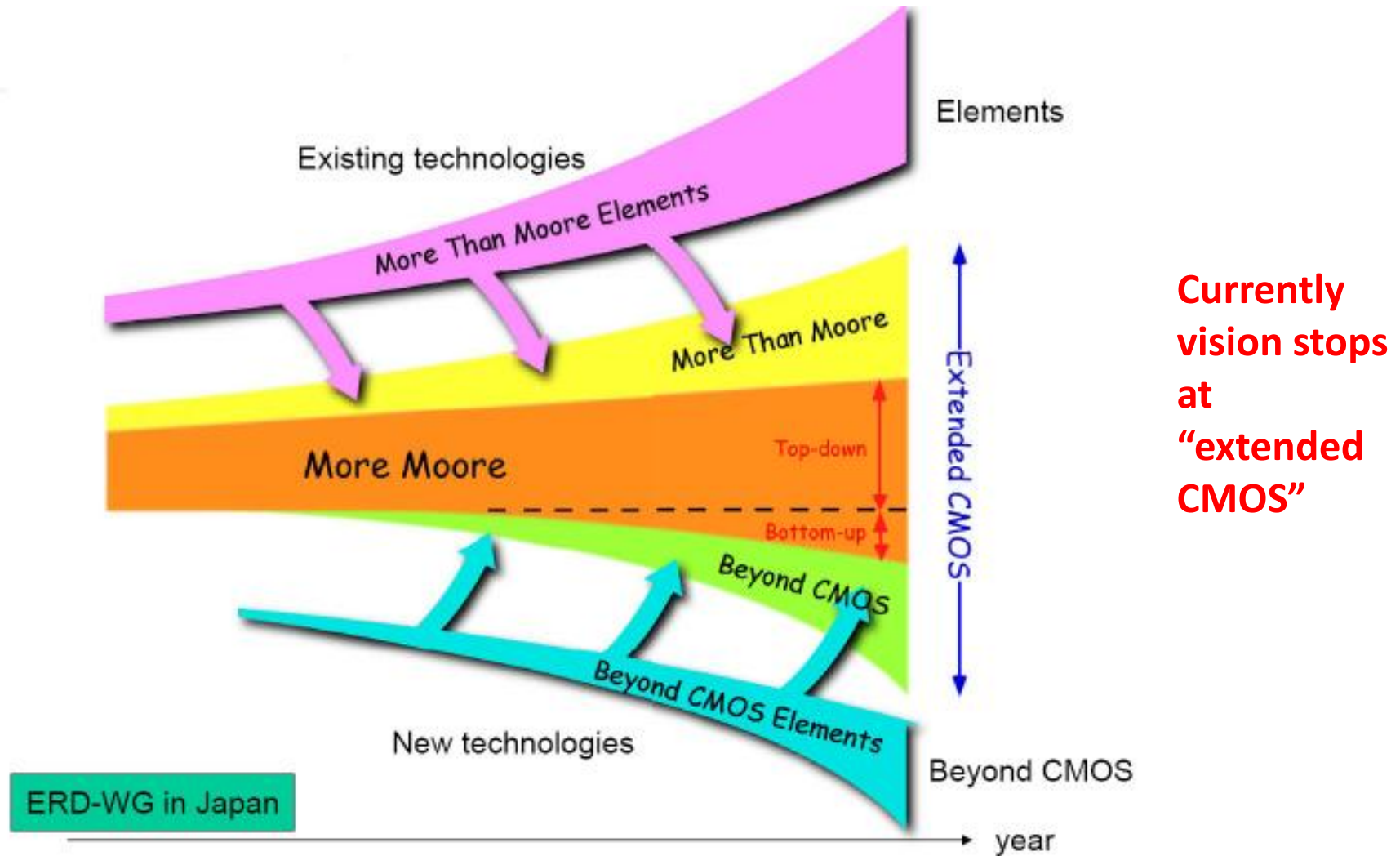
New information processing devices and architectures



FP7 Workshop on Advanced Nanoelectronics Technologies, 11<sup>th</sup> Sept 2009, Brussels

# PERCEIVED ROLE OF BEYOND CMOS TECHNOLOGIES

ITRS-ERD vision on the role of More than Moore and Beyond CMOS elements to foRM future extended CMOS platforms.



FP7 Workshop on Advanced Nanoelectronics Technologies, 11<sup>th</sup> Sept 2009, Brussels

## Workshop series:

- Gather perspectives from a wide range of experts from Europe and beyond
- Arrange for speaker, discussant and rapporteurs
- Document each workshop with presentations and reports
- Build on previous workshop(s)

## Test new methodologies to discuss Beyond CMOS:

- Benchmarking
- SWOT analysis

## Web-based platform:

- Project Communications
- Workshop organisation
- Document repository
- Working Group discussions

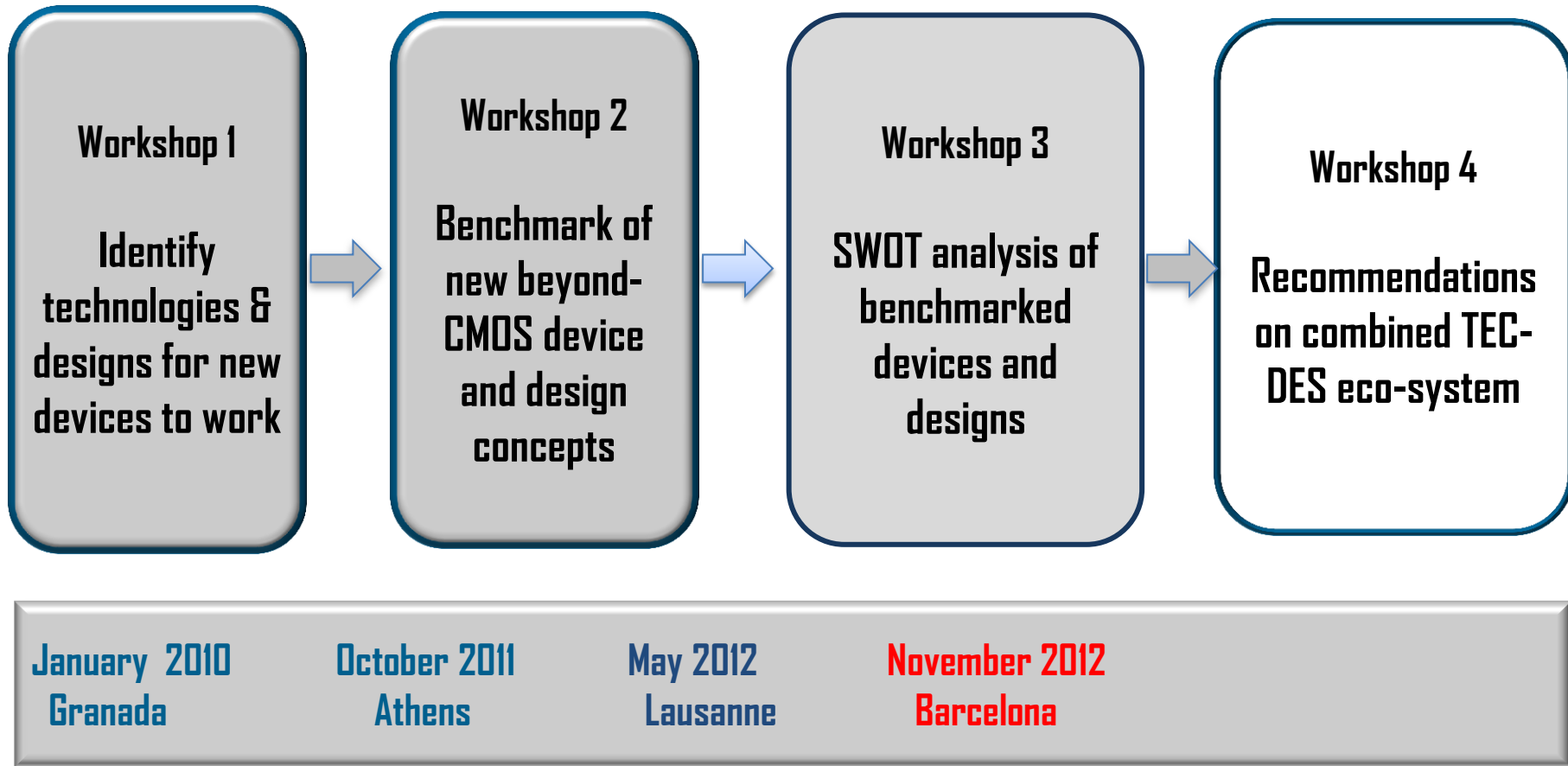
## Dissemination:

- Incorporate the design community and involve the nanoelectronics one.

*And, above all ...  
find ways to involve  
the design  
community.*

# NANO-TEC Workshops timeline

## Main mechanism to reach suitable recommendations



## WORKSHOP 1 Winter 2011 (non-exhaustive list) :

- SRC experience
- **Si-based Nanoelectronics**
- **Compound semiconductor based electronics**
- Carbon-based electronics
- Spintronics & Magneto-electronics
- Molecular electronics / Quantum Computing
- Analogue mixed Design
- **Panel: Bridge to Design**

Nanowires and MEMS/NEMS left for WS2

## Address cross-cutting issues:

Power consumption, manufacturability and cost vs. performance.

## New technologies issues:

Device functionality at the nanoscale needs to be strengthened

Increasing need for new architectures

Alternative concepts to do computation.

## Beyond CMOS design issues:

Variety of nanodevices and materials

Novel circuits and architectures needed to exploit fully nano components.

Mode of operation of such devices?

Multi-scale approach needed in to describe realistic systems.

## Some recommendations:

Graphene and molecular electronics need targeted programs.

Spintronics needs a targeted program on architectures and systemability.

# BENCHMARKING

## WORKSHOP 2:

- **Guardian Angels & Graphene Flagships**
- Graphene
- Spintronics (Memories)
- Molecular electronics
- MEMS
- Solid-state based Quantum Computing
- Nanowires
- Memristors
- **Panel Discussion on Design**

Working Groups  
benchmarked technologies



## Benchmarking Beyond CMOS Devices

Technology	[Wires, graphene, MEMS etc... please insert name]
Gain Signal/Noise ratio Non-linearity	
Speed Power consumption	
Architecture/Integrability (Inputs/outputs, digital, multilevel, analog, size etc.)	
Other specific properties	
Manufacturability (Fabrication processes needed, tolerances etc.)	
Timeline (When exploitable or when foreseen in production)	



# Benchmarking exercise in the US



## NRI Switch Candidates



- 15 nm LV CMOS
- 15 nm HV CMOS
- Excitonic FET
- MTJ Logic Switch
- All Spin Logic
- Graphene PN Junction
- Electronic Ratchet
- Graphene thermal logic
- BDD Architecture
- Nanomagnet logic
- gnrTFET
- InAs TFET
- e-Struct. Modulation Trans
- RAMA
- BiSFET
- RIEFET
- HetTFET
- Spin Wave
- MTJ/STT
- Spin Torque Amplifiers
- Magnetic Domain Wall Logic
- Graphene spin transport
- MOTT Device
- Spin-Injection Hall Effect
- Few Spin Device

Bernstein et al., Device and Architecture Outlook for Beyond CMOS Switches, Proc. IEEE 98 (2010) 2169.



# Benchmarking exercise in US



Circuits used to Benchmark Device



- 
- Inverter with a fanout of 4
  - 2-input NAND with a fanout of 1
  - 32b adder

Bernstein et al., Device and Architecture Outlook for Beyond CMOS Switches, Proc. IEEE 98 (2010) 2169.

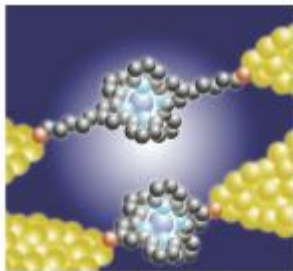
## Aim to a broader scope:

- No direct comparison with CMOS
- Allow for other concepts in addition to digital switches
- Challenge the design community

# Example: MOLECULAR ELECTRONICS (1/3)

D. Vuillaume, 2nd NANO-TEC Workshop

## Single molecule electronics

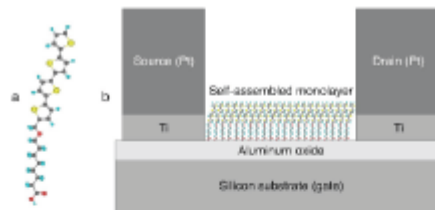


$L < \text{a few nm}$   
 $t < \text{a few nm}$

basic science  
knowledge development

no foreseen applications  
in a reasonable time-scale

## Self-assembled molecular electronics



$L \sim \text{tens nm} - \mu\text{m}$   
 $t < \text{a few nm}$

basic science  
knowledge development

possible applications  
foreseen

## Thin film molecular electronics



$L > \mu\text{m}$   
 $t > \text{few } 10 \text{ nm}$

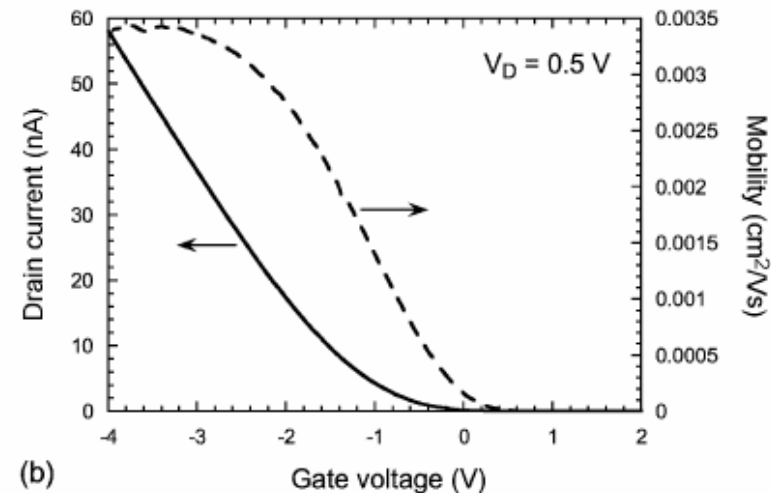
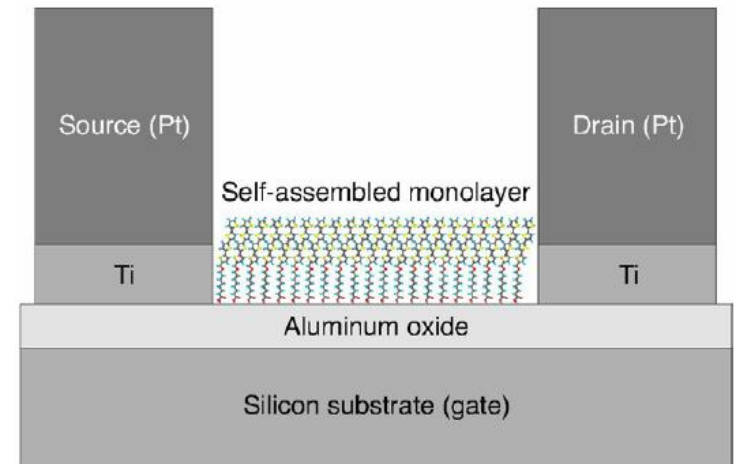
plastic electronics  
(OLED, OFET, OPV)

some products already  
commercialized

# Example: MOLECULAR ELECTRONICS (2/3)

## SAMFET: Self-Assembled Monolayer Field Effect Transistor

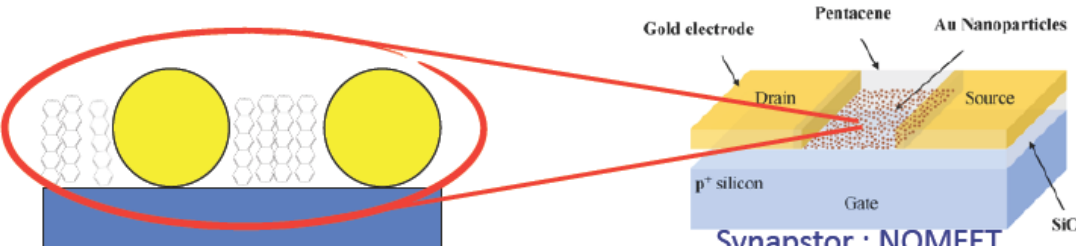
- Built by immersing a Si substrate in a solution of liquid crystalline molecules, resulting in a monolayer of self-assembled semi-conductive molecules.
- Molecules stand upright. Conduction takes place by charges jumping from one molecule to the other.
- As the length of the SAMFET increased, its conductivity decreases exponentially.
- The SAMFET can be used to make sensors that give a large signal triggered by a small change.



# Example: MOLECULAR ELECTRONICS (3/3)



## Benchmarking Beyond CMOS Devices

<b>Technology</b>	Molecular Electronics D. Vuillaume, CNRS & University of Lille
<b>Gain</b>	Ok with SAMFET (to be optimized), 2-terminal junction: low current
<b>Signal/Noise ratio</b>	Noise not yet studied (a few publications)
<b>Non-linearity</b>	Mole
<b>Speed</b>	Low
<b>Power consumption</b>	Low
<b>Architecture/Integrability</b> (Inputs/outputs, digital, multilevel, analog, size etc.)	Mole funct 
<b>Other specific properties</b>	Almost infinite combination of molecules, adjustable by chemistry, specific design (1 molecule = 1 function)
<b>Manufacturability</b> (Fabrication processes needed, tolerances etc.)	Solution processing, compatible with flexible substrate. Defect control? Large variability (but not a problem if we envision artificial neural networks)
<b>Timeline</b> (When exploitable or when foreseen in production)	> 5 – 10 years (if ever?)

## General recommendation:

- Refine the benchmarking methodology to cover a wider range of Beyond CMOS technologies and design approaches.
- Memory or switching functions of FET-like devices found too restrictive.
- In some cases benchmarking needs to be application-specific.

## Common specific recommendation:

- The design component must be built-in from the very beginning.
- Make use of the 3<sup>rd</sup> dimension, eg, MEMS
- Initially seek to integrate on a Si platform, eg. Quantum computing
- Variability and systemability seen as main challenges.
- Thermal issues and stability need to be addressed.
- Design tools need to incorporate multi-physics and multi-scale approaches.

# SWOT Analysis

## WORKSHOP 3:

- Graphene
- Spintronics
- Molecular electronics
- MEMS
- Solid-state based Quantum Computing
- Nanowires
- Neuromorphic Computing
- **Panel Discussion “From technology to Applications”**

### Strengths

- ....
- ....
- ....

### Weaknesses

- ....
- ....
- ....

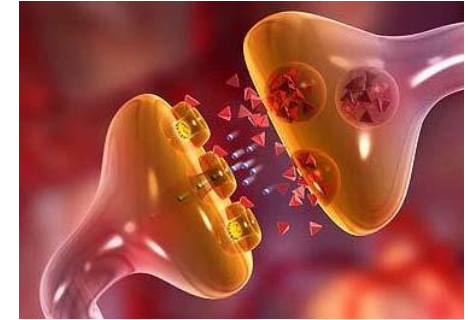
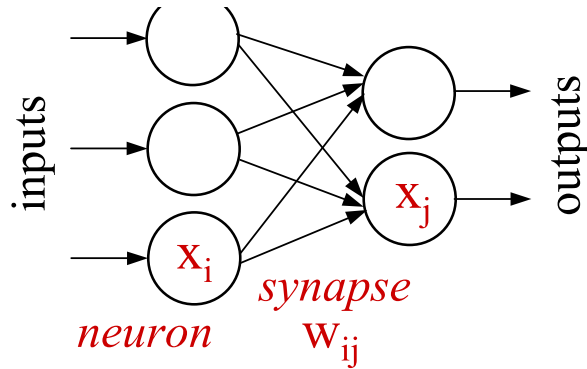
### Opportunities

- ....
- ....
- ....

### Threats

- ....
- ....
- ....

# EXAMPLE: SWOT Analysis of Neuromorphic Computing



- **synapses should have a memory** : the weights have to be stored (non-volatility)
- **synapses should be small** :  $10^4$  synapses/neuron in human brain
- **synapses should be plastic** : synaptic plasticity

Biological synapse : change in strength in response to either use or disuse of transmission

Artificial synapses : the weights  $w_{ij}$  should be adjustable

a learning rule specifies how to adjust the weights for a given input/output pair

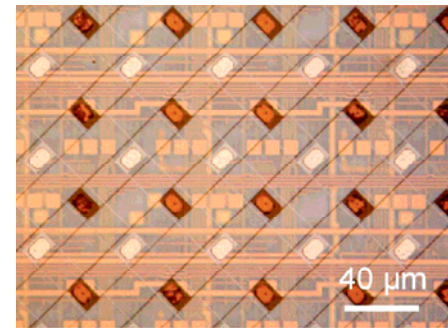
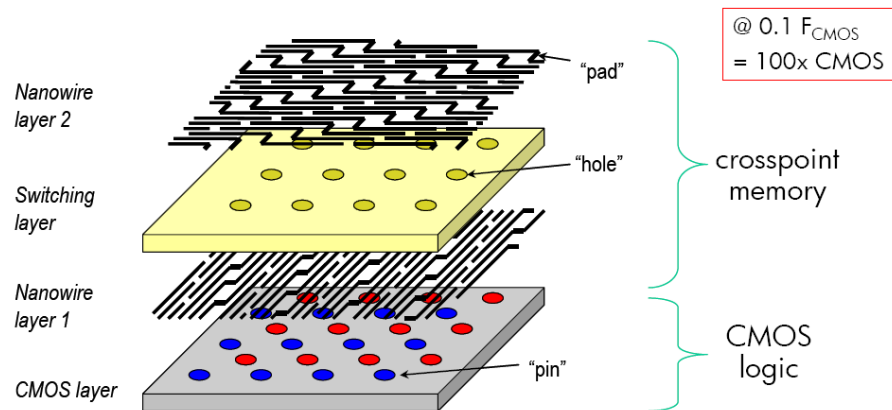
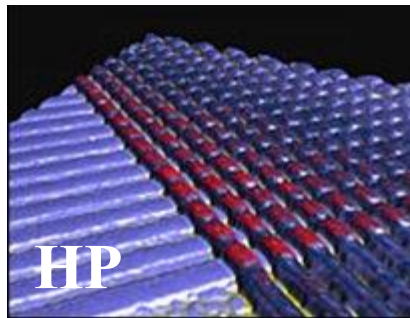
J Grollier, 3<sup>rd</sup> NANO-TEC workshop



# Example: SWOT Analysis of Neuromorphic Computing

- Memristors have a memory :  
they directly store the synaptic weights ( $w = \text{conductance}$ )
- Memristors are small ( $< 50 \times 50 \text{ nm}^2$ )

**ex : CMOS “neurons” + memristive “synapses”**



Xia *et al.*, Nanoletters (2010)

*memristor crossbar arrays*

**No demonstration yet of operational mixed memristor/CMOS cognitive chip**

J Grollier, 3<sup>rd</sup> NANO-TEC workshop

# EXAMPLE: SWOT Analysis of Neuromorphic Computing

## Strengths

- speed
- low power
- defect tolerance

## Weaknesses

- interconnect
- programming
- design : to be invented
- control device stochasticity

## Opportunities

- use differently memory devices
- accelerators for specific functions to interface in heterogeneous multi-core architectures
- adaptive architectures, able to compute with incomplete data → robotics, unmanned vehicles etc.

## Threats

- the density cannot be reached
- the interconnection problem cannot be solved
- heat management

J Grollier, 3<sup>rd</sup> NANO-TEC workshop

## Considering all technologies discussed:

<b>Strengths</b> <ul style="list-style-type: none"><li>• Application perspectives</li><li>• Building blocks for innovation in nanoelectronics</li><li>• European industrial/academic ecosystem</li></ul>	<b>Weaknesses</b> <ul style="list-style-type: none"><li>• Physical constraints</li><li>• Compatibility issues with conventional technology</li><li>• Reliability, variability</li></ul>
<b>Opportunities</b> <ul style="list-style-type: none"><li>• Design of circuits and systems</li><li>• 3D integration of multifunctional systems</li><li>• Industrial/academic cooperation</li></ul>	<b>Threats</b> <ul style="list-style-type: none"><li>• Gap to industrial needs?</li><li>• 'CMOS competition'</li><li>• Manufacturability</li></ul>

## Based on panel discussions and presentations:

- Strands reflect current approaches in the design community
- Material → property → function → application
- Modelling → design
- Device → systemability → system

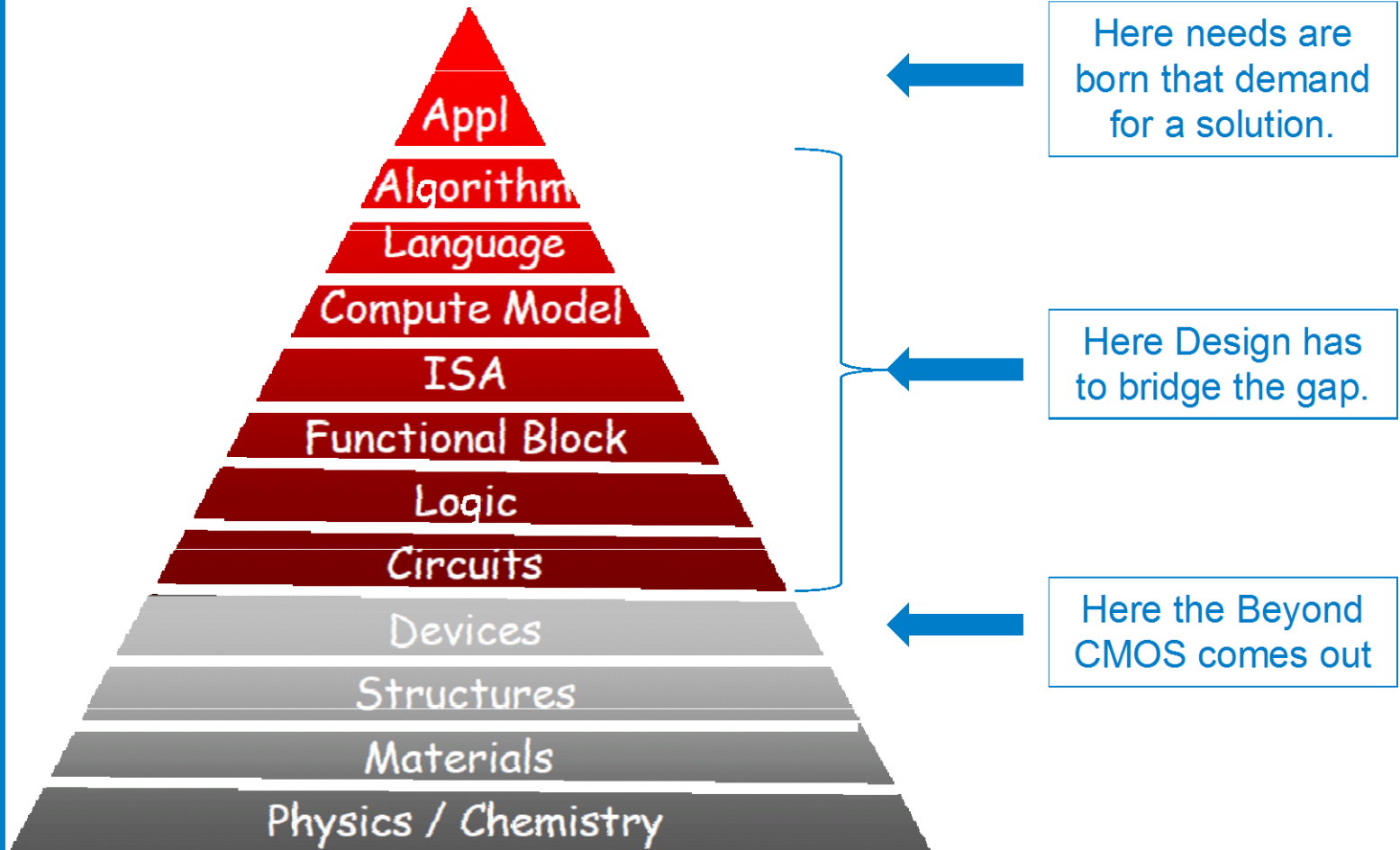
## From modelling to design

**We can simulate transport in molecular and semiconducting nanostructures quite reliably, accounting for charging effects, dissipation, screening as long as the molecular systems consist of a sufficiently small number of atoms,**

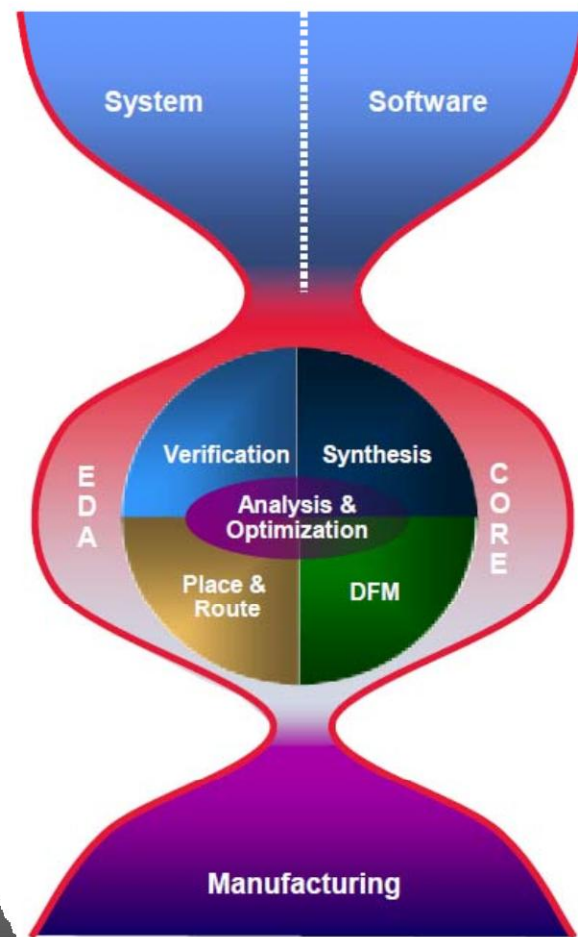
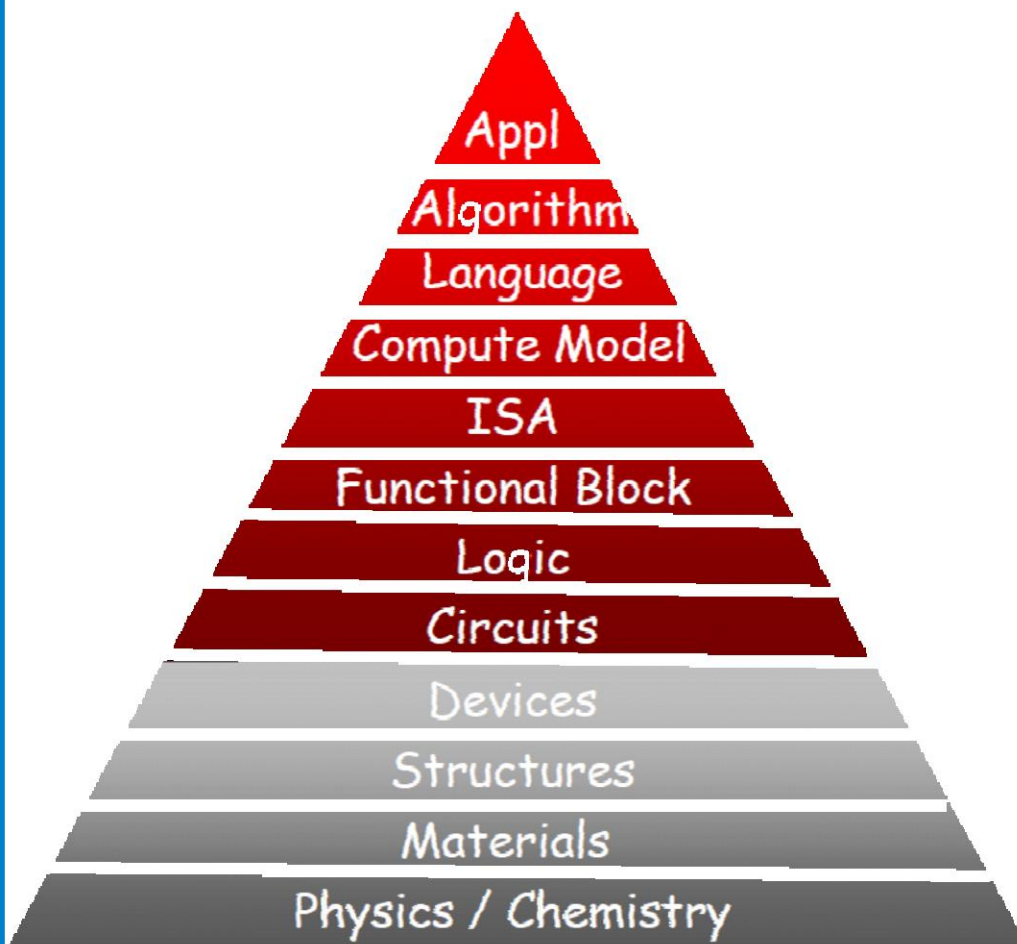
**but**

**the simulation of realistic systems, especially in terms of the contacts and in general the coupling with the external environment is still a problem**

# The Food Pyramid



# A lot of work is done to bridge the gap



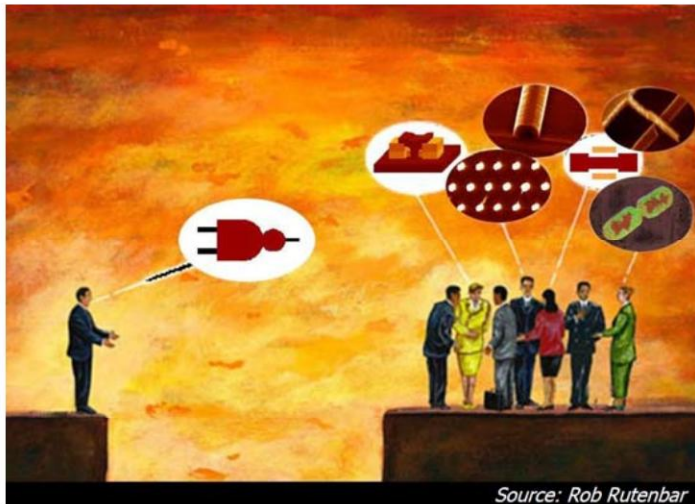
## but most of Design today focuses on the “Middle”



# The Gap on the bottom is known!

It is between device and system.

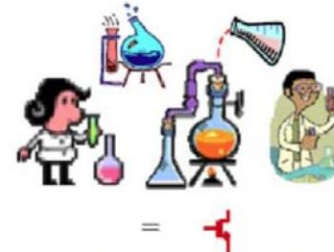
**SYSTEMABILITY:**  
The ability to economically design and manufacture reliable systems from the interaction of devices fabricated in a given technology.



Source: Rob Rutenbar

## BENCHMARKING BEYOND CMOS DEVICES

Beyond CMOS device inventor



Hey, here's a great new device ...

- ❖ It's really cool! It looks useful!
- ❖ We actually made one! It worked!

The CMOS designer



... but I can't do **design** with them

- ❖ I don't understand them.
- ❖ You can't characterize them, model them, simulate them, make them in volume, ...

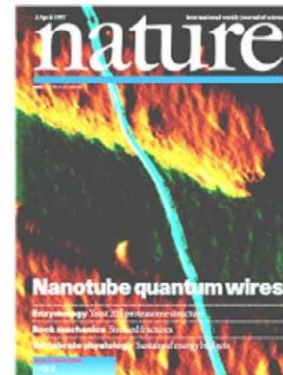
Source: W. Joyner, IBM

imec

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Source : D. Verkest, NANO-TEC-WS2, 2011

## Ultimate Measures of Success ...



For the **technologist**:  
I/V curve in Nature  
(Rob Rutenbar, 2004)



For the **circuit designer**:  
Best Paper Award at ISSCC





# A Bridge to the system is needed

**SYSTEM = COMPUTATION, STORAGE, INTERCONNECT, I/O, (ANALOG)**

Every contender

- ▶ Must add value to one or more of the 4 system functions and be compatible with the others
- ▶ All-in throughput/Watt and/or transactions/Joule must beat CMOS at time of manufacturing at equivalent or lower cost
- ▶ System level manufacturability, reliability, testability must beat ultimate CMOS solutions
- ▶ Room temperature operation is mandatory
- ▶ Device variability must be mitigated and modeled and cost efficient error resilient design solutions must be available
- ▶ Design methods and tools must be in place supporting design from device to system. Design tool development time is 3x technology development time.

Source :  
D. Verkest,  
NANO-TEC-WS2, 2011

## BENCHMARKING BEYOND CMOS DEVICES

Beyond CMOS device inventor

The CMOS designer



Source: W. Joyner, IBM



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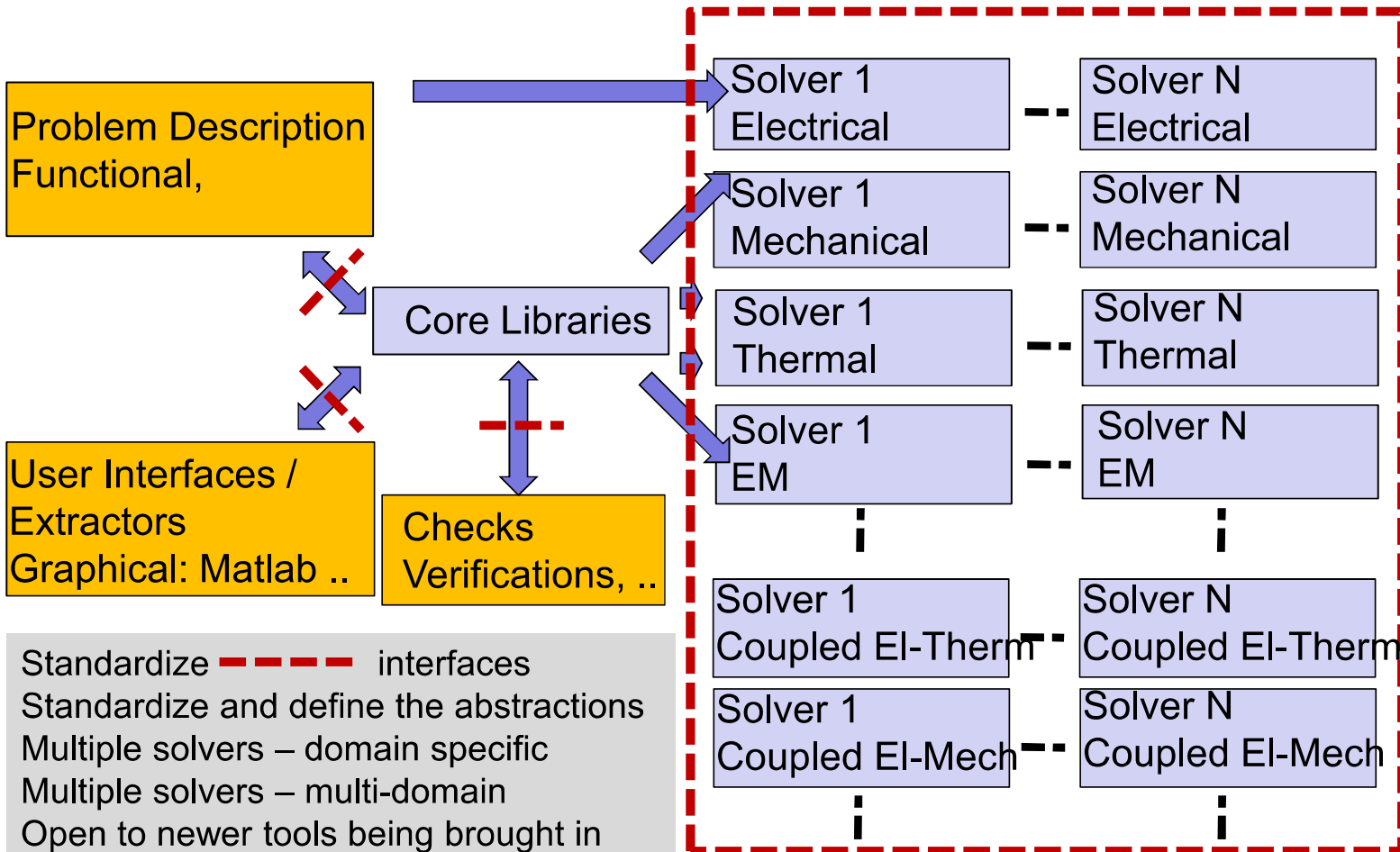
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# A POSSIBLE TECHNOLOGY & DESIGN INFRASTRUCTURE

## *Build A New Open Infrastructure*

S Tiwari



Tiwari\_05\_Lausanne.pptx

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# A BOLD SUGGESTION (1/2)

## An “experiment”:

- Develop methods to ensure the technology gap is bridged
- Cluster three pilot project in Beyond CMOS technology-design
- Better still, launch two or three super Integrated Projects
- If clusters then projects each dealing with one of charge-based, non-charge based and a computing paradigm -- at different stages in the TRL.
- If super IPs, then cluster them anyway in joint annual working sessions.
- In either case these should be ideally supported by a pilot distributed technology-design research infrastructure

# A BOLD SUGGESTION (2/2)

Application &  
Technology-  
specific projects

Common  
opportunities



Project 1  
Charge-based  
Technology

Project 2  
Non-charge-  
based  
Technology

Project 3  
New Computing  
Paradigm

Low power

Si-compatible

New Design Tools

Beyond CMOS-oriented Technology-Design Research Infrastructure

# TODAY's SCOPE

## Includes presentations:

- Summary of discussions and recommendations per
  - Charge-based state variable
  - Non-charge-based state variables
  - New computing paradigms
  - Ecosystem technology
  - Design and technology integration
- Working groups to discuss and refine recommendations → final report for the Commission and the community of Beyond CMOS in the combined ecosystem.

## AND

- Perspective in Europe and the USA
- Scientific presentations on Neuromorphic computation and Topological Insulators